

LNJ810C67RA

Hight Bright Surface Mounting Chip LED

SV (Side View) -Case Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	50	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +85	$^\circ\text{C}$

■ Lighting Color

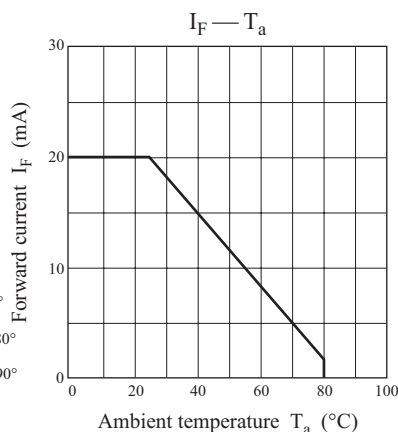
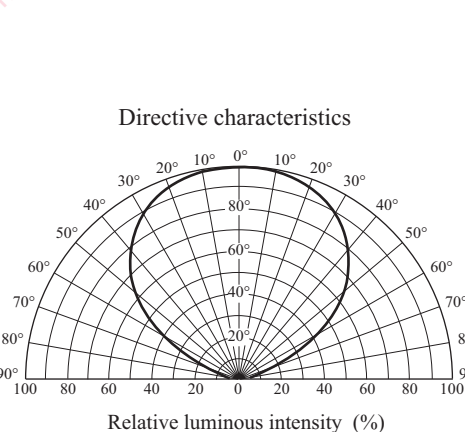
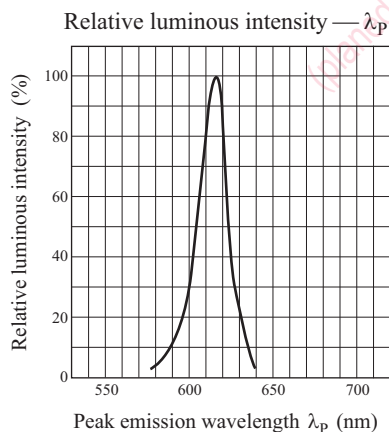
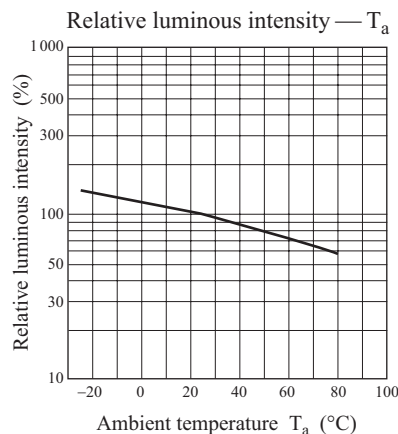
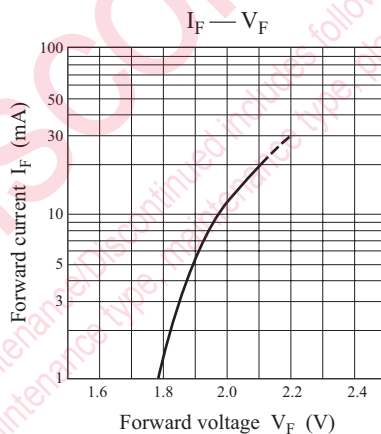
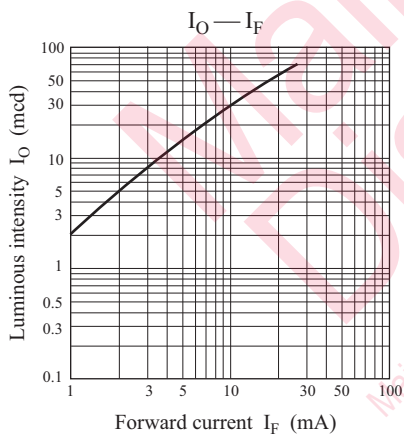
- Soft Orange

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

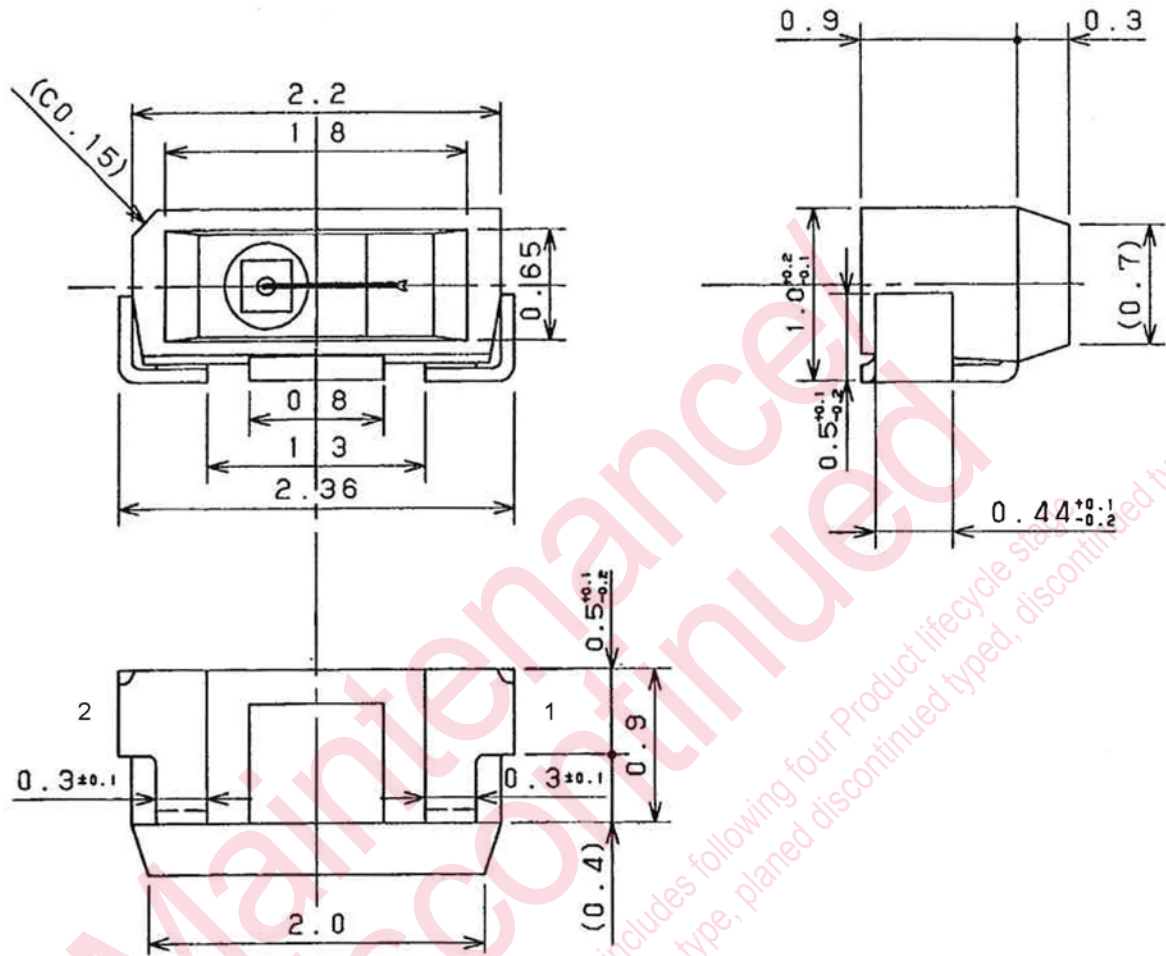
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 10 \text{ mA}$	24	30	55	mcd
Reverse current	I_R	$V_R = 4 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10 \text{ mA}$		1.95	2.5	V
Peak emission wavelength	λ_p	$I_F = 10 \text{ mA}$	600	615	625	nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		20		nm

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

LLDFSR2J1000



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued includes following four Product lifecycle status (planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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